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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Kazuhiko Ueda et al.

Serial No.: 10/586,858

Art Unit: 1796

Filed : October 27, 2006

Examiner: LOEWE, ROBERT S

Title : PRESSURE SENSITIVE ADHESIVE COMPOSITION

DECLARATION UNDER RULE 132

Honorable Commissioner of Patents and Trademarks,
Alexandria, Virginia 22313-1450

Sir:

I, Toyohisa Fujimoto, a citizen of Japan and having postal mailing address of c/o Kaneka Corporation, 1-8, Miyamae-cho, Takasago-cho, Takasago-shi, Hyogo 651-2137, Japan, declare and say that:

In March, 1999, I was graduated from Graduate School of Engineering, Tohoku University, and received a master's degree in the field of chemistry;

Since April, 1999, I have been employed by Kaneka Corporation and engaged in the work of research and development of modified silicone for sealing materials in High Performance Polymers Division;

I am familiar with the technical field of the present invention;

I respectfully submit herewith my exact report;

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Experiments

Pressure sensitive adhesive compositions were prepared by mixing the components shown in Table 1. Components were the same as those used in the Examples and Comparative Examples of the present application. Pressure sensitive adhesive films were prepared and evaluated as described in page 19, lines 17 to 20 and page 20, lines 19 to 27 in the specification of the present application. Results are shown in Table 1.

Table 2 indicates the results of Examples 1 to 3 and Comparative Examples 1 to 3 of the present application for reference.

In Tables 1 and 2, amounts of (C) component and curing agent are relative to combined total of 100 parts by weight of (A) component and (B) component.

Results

As shown by Experiment 7, the pressure sensitive adhesive composition provides a sufficient adhesive strength even when the amount of (B) component is 100 parts by weight relative to 100 parts by weight of (A) component.

As shown by Experiments 8 and 9, the pressure sensitive adhesive composition provides a sufficient adhesive strength even when a small amount of (B) component is used.

As shown by Experiment 10, the pressure sensitive adhesive composition provides a sufficient adhesive strength even when the amount of (C) component is 30 parts by weight relative to a combined total of 100 parts by weight of (A) and (B).

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Table 1

		Mn	Si group (eq)	Experiment 7	Experiment 8	Experiment 9	Experiment 10
(A) component	A-1	31,000	0.75	100	100	100	100
	A-2	26,000	0.85				
Comparative Component	A-3	10,800	0.75				
(B) component	B-1	4,300	0.4	100	7.5	3	30
	B-2	4,000	0.5				
Comparative Component	Actool P-23	4,000	0				
(G) component	YS Polyster S145	Amount relative to combined total of 100 parts by weight of (A) and (B)		50	50	50	30
Toluene		Amount relative to combined total of 100 parts by weight of (A), (B) and (C)					
Curing Agent	Orgatix TC-100	Amount relative to combined total of 100 parts by weight of (A), (B) and (C)		4	4	4	4
Results in the specification	Viscosity	(Pa·s)					
	Adhesive strength	(N/25mm)					
Additional data	Viscosity	(Pa·s)		89.0	455.3	515.3	93.4
	Adhesive strength	(N/25mm)		30.1	23.2	18.3	13.2

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Table 2

		Mn	Si group (eq)	Example 1	Example 2	Example 3	Comparative Example 1	Comparative Example 2	Comparative Example 3
(A) component	A-1	31,000	0.75	100	100		100	100	
	A-2	26,000	0.85			100			
Comparative Component	A-3	10,800	0.75						100
(B) component	B-1	4,300	0.4	30		40			
	B-2	4,000	0.5		40				
Comparative Component	Actool P-23	4,000	0				30		
(C) component	YS Polyster S145	Amount relative to combined total of 100 parts by weight of (A), (B) and (C)		50	50	50	50	100	80
Toluene		Amount relative to combined total of 100 parts by weight of (A), (B) and (C)						50	
Curing Agent	Orgatix TC-100	Amount relative to combined total of 100 parts by weight of (A), (B) and (C)		4	4	4	4	4	4
Results in the specification	Viscosity	(Pa·s)		280.2	225.6	232.2	279.5	918.4	290.4
	Adhesive strength	(N/25mm)		30.6	25.4	26.8	7.6	10.2	9.8

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I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signed this 19th day of May, 2011

Toyohisa Fujimoto

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